

AMENDMENT(S) TO THE SPECIFICATION

Please replace paragraph [0022] at page 6, with the following rewritten paragraph:

[0022] Compression assembled semiconductor package 10 also includes control lead 14 which extends through the body of annular insulation ring 30 to the exterior thereof. Preferably, control lead 14 comprises a copper tab. In the first embodiment of the present invention, a bond wire 40 is electrically connected at one end thereof to an upper exposed surface of control lead 14 which is disposed within annular insulation ring 30. The other end of bond wire 40 is connected to control electrode 24 of semiconductor die 20. Top pole piece 12 includes a groove 13 which allows bond wire 40 to reach control electrode 24 of semiconductor die 20 [[whence]] where bond wire 40 is connected to control lead 14. Together, bond wire 40 and control lead 14 form a control signal carrier that transmits from a control circuit control signals to control electrode 24 of semiconductor die 20